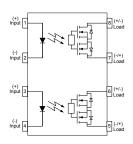
# **APSEMI®**

Parameter	Symbol	Rating	Units	
Load Voltage	VL	350	V	
Load Current	lL .	0.12	Α	
On-Resistance	Ron	17	Ω	
I/O Breakdown Voltage	V/Io	2500	Vrms	



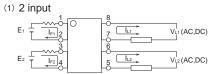


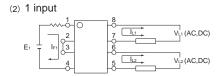
SOP-8



1,3. LED Anode

2,4. LED Cathode 5,6. Drain (MOS FET) 7,8. Drain (MOS FET)





### APSEMI PhotoRelays

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- · resistant to vibration and impact AC or DC load
- switching
- Small package size

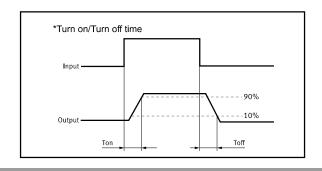
## **Applications**

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- **Energy Management**
- Reed Relay EMR Replacement
- Programmable Controllers

#### **TPYES**

Catagoni	Output Rating		Doolsons	Part No.	Poolsing Overtity	
Category	Load Voltage	Load Current	Package	Part No.	Packing Quantity	
AC/DC	350V	0.12A	SOP-8	GAQW210S	2000pcs /reel	





## Absolute Maximum Ratings (Ta = 25°C)

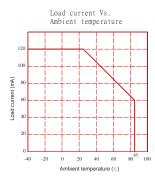
	Item	Symbol	Va <b>l</b> ue	Units	Note
	Continuous LED Current	<b>I</b> F	50	mA	
Input	Peak LED Current	<b>I</b> FP	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	VR	5	V	
	Input Power Dissipation	Pın	75	mW	
	Load Voltage	V∟	350	V(AC peak or DC)	
	Load Current	l.	0.12	Α	
Output	Peak Load Current	Peak	0.6	Α	100ms(1 pulse)
	Output Power Dissipation	Pout	300	mW	
Total Power	Dissipation	P⊤	350	mW	
I/O Breakdov	vn Vo <b>l</b> tage	V <sub>I/O</sub>	2500	Vrms	RH=60%, 1min
Operating Te	emperature	Торг	-40 to 85	℃	
Storage Tem	perature	T <sub>stg</sub>	-40 to 100	℃	
Pin Soldering	g Temperature	Tsol	260	°C	10 sec max.

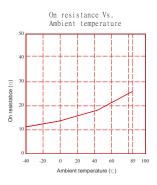
## Electrical Characteristics (Ta = 25°C)

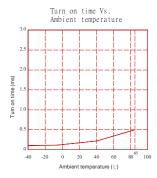
	Item	Symbol	MIN.	TYP.	MAX.	Units	Conditions
	LED Forward Voltage	VF		1.2	1.4	V	I⊧=10mA
	Operation LED Current	Fon		0.5	1.0	mA	
Input	Recovery LED Current	Foff		0.35	0.5	mA	
	Recovery LED Voltage	V <sub>Foff</sub>	0.7			٧	
							I⊧=5mA,I∟=Max
Output C	On-Resistance	Ron		17	24	Ω	Time to flow is within 1 sec.
	Off-State Leakage	Leak			1	uA	V∟=Rating
	Current	ILOUN					VE Training
	Output Capacitance	Cout		41		pF	V∟=0, f=1MHz
Transmis	Turn-On Time	Ton		0.05	0.3	ms	I⊧=5mA, I∟=Max
sion	Turn-Off Time	Toff		0.05	0.2	ms	
Counted	I/O Isolation Resistance	R <sub>I/O</sub>	10 <sup>10</sup>			Ω	DC500V
Coupled	I/O Capacitance	Ci/o		0.8	1.5	pF	f=1MHz

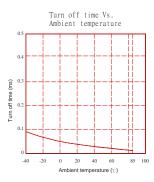
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF  $\geq$ 5mA and  $\leq$ 30mA

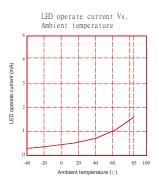
## **Engineering Data**

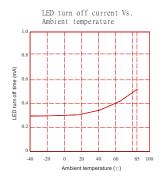


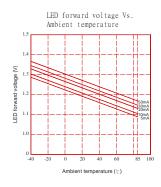


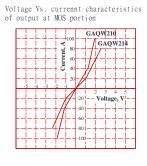


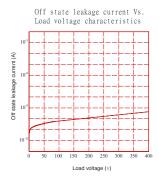


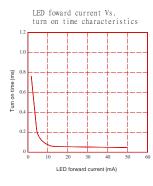


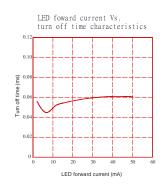


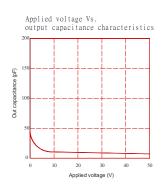








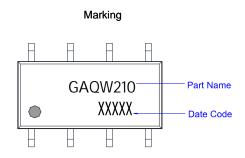


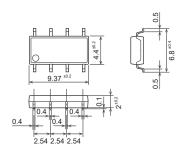




## Dimensions and SOP-8 Package Unit: mm

## Surface mount terminal type



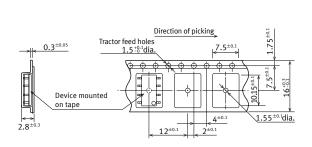


## Recommended mounting pad (Top view)

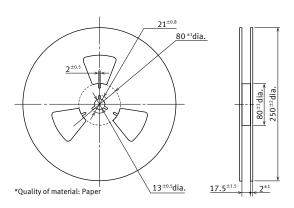


#### Tape dimensions (tape reel)

Tape dimensions (Unit: mm)



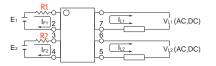
## Dimensions of paper tape reel (Unit: mm)





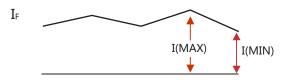
#### **Using Methods**

Examples of resistance value to control LED forward current (IF=5mA)



E1 E2	R1 R2(Approx)			
3.3V	300 Ω			
5.0V	600 Ω			
12V	1.9KΩ			
24V	4.1K Ω			

LED forward current must be more than 5mA, at I(MIN), and less than 30mA, at I(MAX).



#### **Recommended Operating Conditions**

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

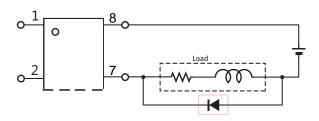
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	lF	5.0	7.0	30	mA

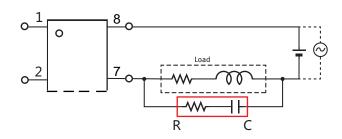
#### **Protection Circuit**

Output spike voltages:if an inductive load generates spike voltages which exceed heabsolute maximum rating, the spike voltage shall be limited.

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.